IN THE SPECIFICATION:

Please amend paragraph [0026] in the specification as follows:

[0026] Fig. 2 is a diagram showing the structure of the conductive material 52 in the semiconductor laser apparatus 1 according to the first embodiment. Here, the area (a) shown in Fig. 2 is a perspective view showing the conductive material having a mesh structure applied to the first embodiment, the area (b) corresponds to the cross-section along line [[I-II]] I-I shown in the area (a) and is a view showing an example of having a circular-shaped wire material in cross-section of the mesh structure, and the area (c) corresponds to the cross-section along line [[I-II]] I-I shown in the area (a) and is a view showing an example of having a rectangular-shaped wire material in cross-section of the mesh structure.

Please amend paragraph [0027] in the specification as follows:

[0027] As shown in the area (a) of Fig. 2, the conductive material 52 is a circular material having a diameter capable of covering the cross-section of the flow path of the insulating piping 40, and has a structure knitted in a lattice. A variety of materials such as copper, stainless steel, and aluminum are applicable to the material of the conductive material since the refrigerant 40 consists of a fluorocarbon having non-reactivity. Also, as shown in the area (b) of Fig. 2, the cross-section in parallel to the flow or stream line of the refrigerant 40 of the conductive material 52 (corresponding to the cross-section along line [[I-II]] I-I in the area (a)) may have a circular figure. Alternatively, as shown in the area (c) of Fig. 2, the cross-section in parallel to the flow or stream line of the refrigerant 40 of the conductive material 52 (corresponding to the cross-section along line [[I-II]] I-I in the area (a)) may have a rectangular figure. With the above-mentioned mesh structure, the conductive material 52 has an expanded

surface area coming in contact with the refrigerant, thereby enhancing an advantageous effect discharging static electricity charged in the conductive material. On the other hand, the refrigerant 40 flowing inside the insulating piping 50 leads to pass through the pattern of the mesh. It should be noted that when the form of the conductor 52 provides a structure with an enlarged contact area with the refrigerant 40 and passing freely through the refrigerant 40, it is not limited to the aforementioned mesh structure.

Please amend paragraph [0054] in the specification as follows:

[0054] The area (a) shown in Fig. 10 is a perspective view showing the structure of a mesh-shaped conductive material applied to the third embodiment, and the area (b) corresponds to the cross-section taken along line [[I-II]] I-I in the area (a) and is a view showing an example in which the cross-section of a wire material in the mesh structure has a streamline shape. As shown in the area (a) of Fig. 10, a conductive material 52' has a mesh structure. However, as shown in the area (b), the cross-section in parallel to the stream line of an insulating piping 50 of a conductive material 52' (corresponding to the cross-section taken along line I-II depicted in the area (a)) has a streamline shape. In this way, the occurrence of the vortex in the following flow of the conductive material 52' can be avoided. In addition, since the resistance of the conductive material 52' is suppressed small, the change of the flow velocity passing through the conductive material 52' becomes small, thereby preventing the occurrence of the cavitation.